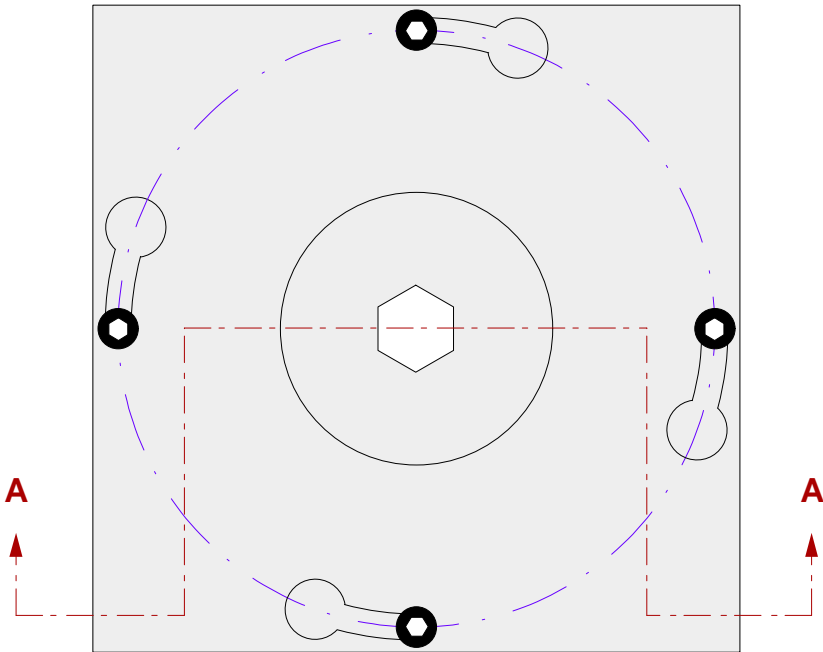


SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

FEATURES:

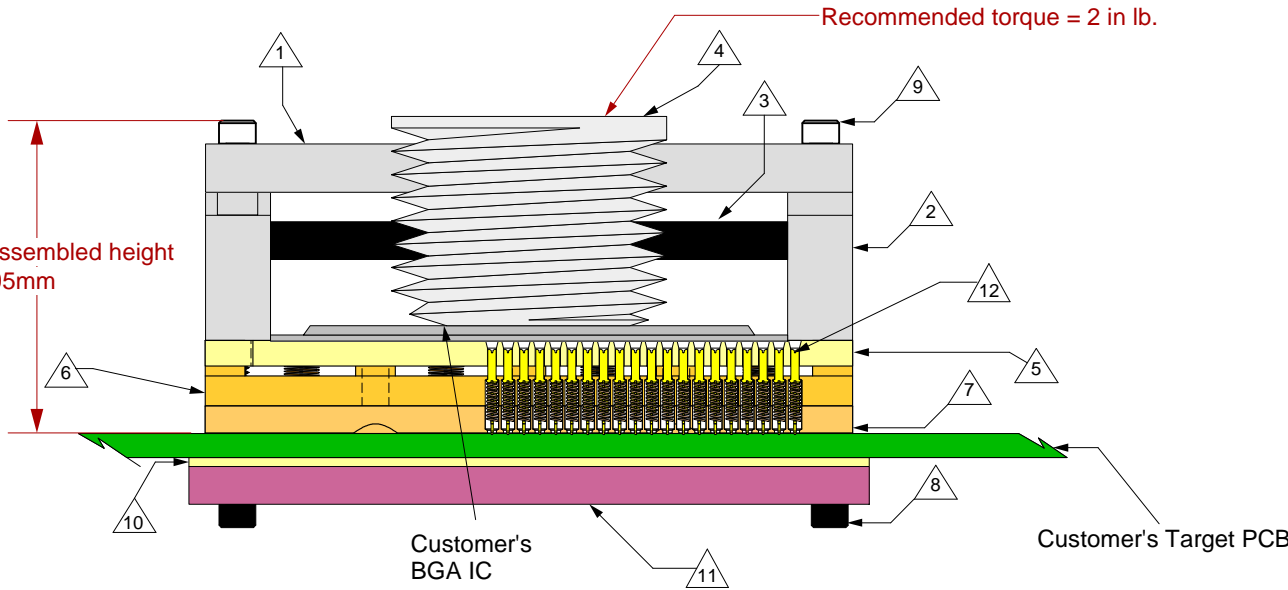
- Wide temperature range (-55C to +180C)
- High current capability (up to 8A)
- Excellent signal integrity at high frequencies
- Low and stable contact resistance for reliable production yield
- Highly compliant to accommodate wide co-planarity variations
- Automated probe manufacturing enables low cost and short lead time

Top View




Approx Assembled height
16.95mm

Side View
(Section AA)

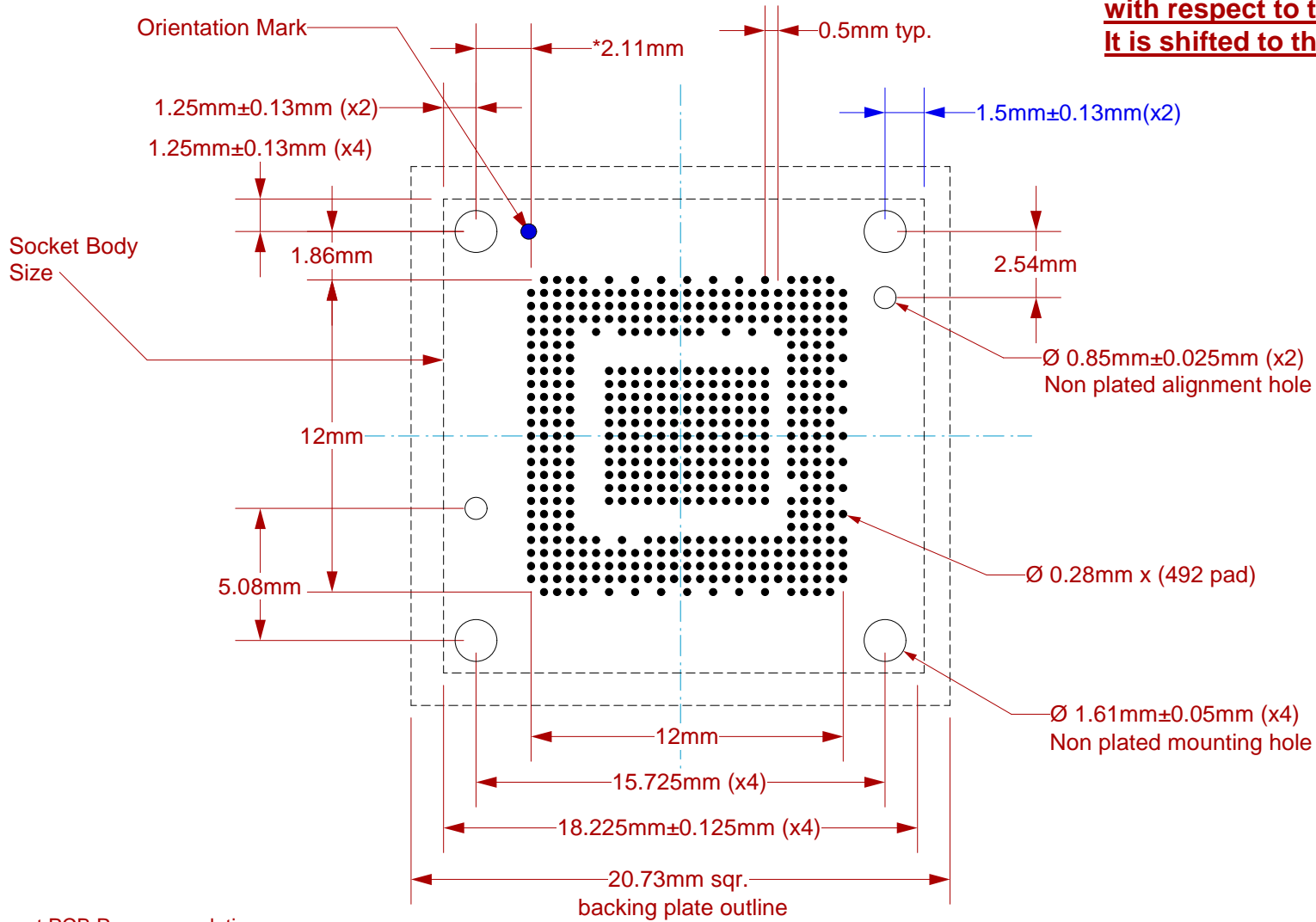


- 1 Socket Lid: Nickel plated Aluminum
Thickness = 2.5mm.
- 2 Socket base: Ni plated Aluminum.
Thickness = 5mm.
- 3 Compression Plate: Ni plated Aluminum.
Thickness = 2.5mm.
- 4 Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm.
- 5 Top guide: Ceramic filled Peek
- 6 Middle guide: Ceramic filled Peek
- 7 Bottom Guide : Ceramic Filled Peek
- 8 Socket base screw: Socket head cap, Alloy steel with
black oxide finish, 0-80 fine thread , 12.7mm long.
- 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread.
- 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 11 Backing Plate: Ni plated Aluminum.
Thickness = 4mm.
- 12 Pogo pin: SBT BGA 0.5mm

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	Drawing: M. Tully	Date: 4/2/2013		
	File: SBT-BGA-7006 Dwg	Modified:		

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View




***Note: BGA pattern is not symmetrical with respect to the mounting holes. It is shifted to the right by 0.25mm.**

Target PCB Recommendations

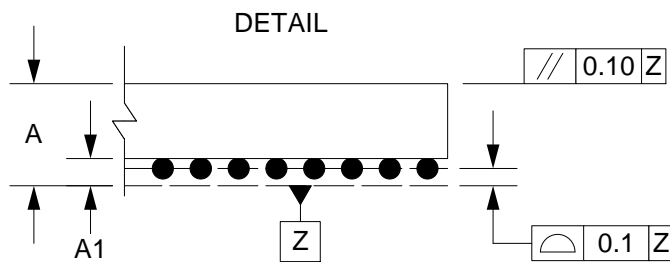
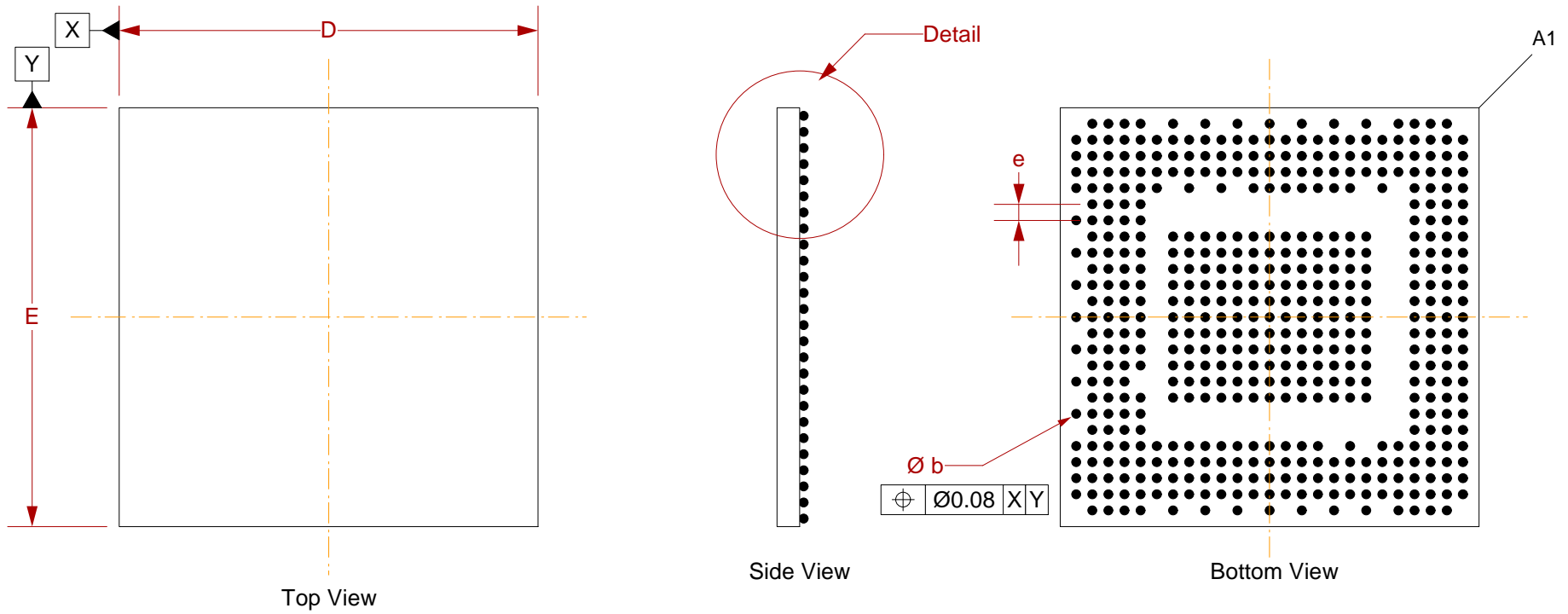
Total thickness: 1.6mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

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		Drawing: M. Tully		Date: 4/2/2013		
		File: SBT-BGA-7006 Dwg		Modified:		

Compatible BGA Spec




1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

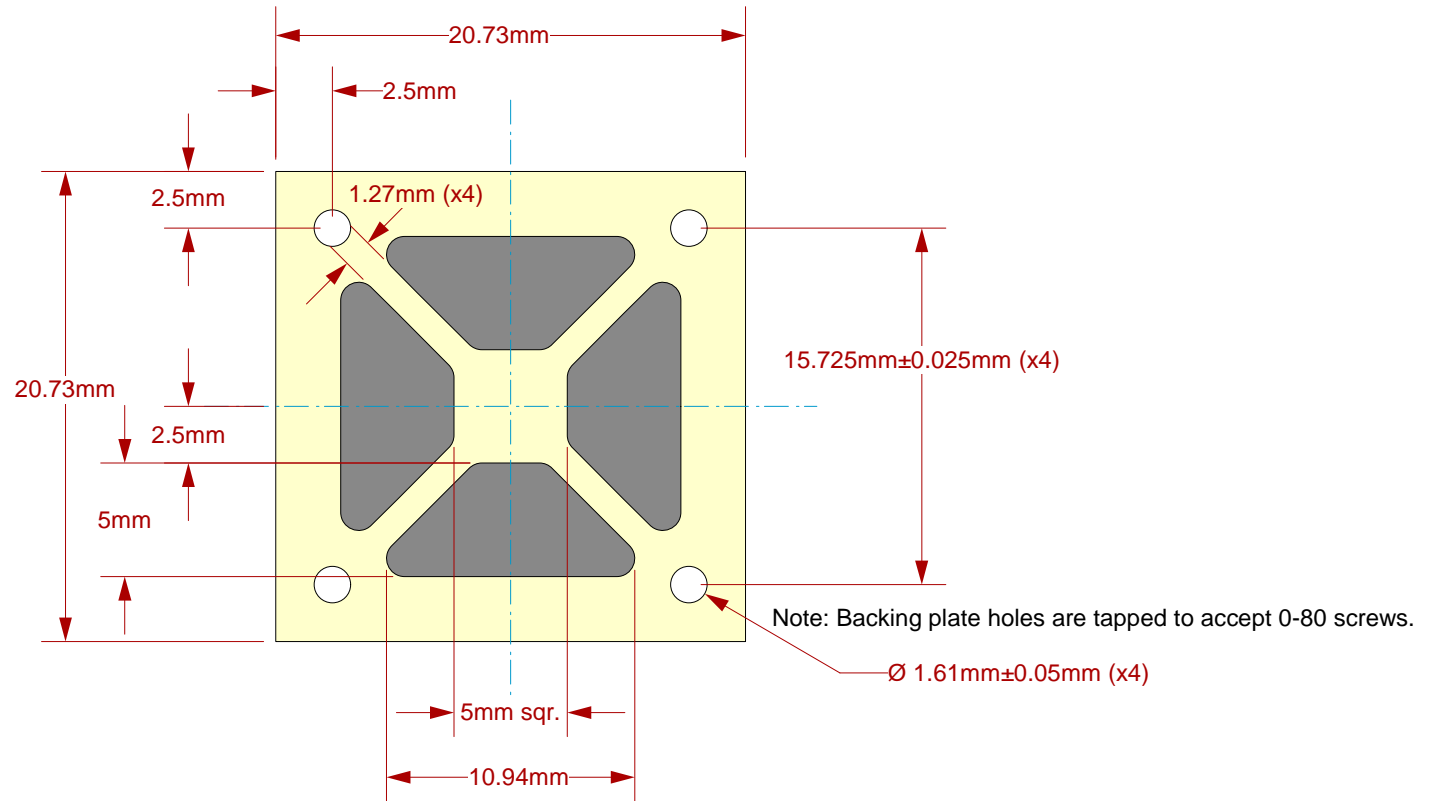
DIM	MIN	MAX
A		1.35
A1	0.15	0.35
b		0.40
D	13.0 BSC	
E	13.0 BSC	
e	0.5 BSC	

25 x 25 array

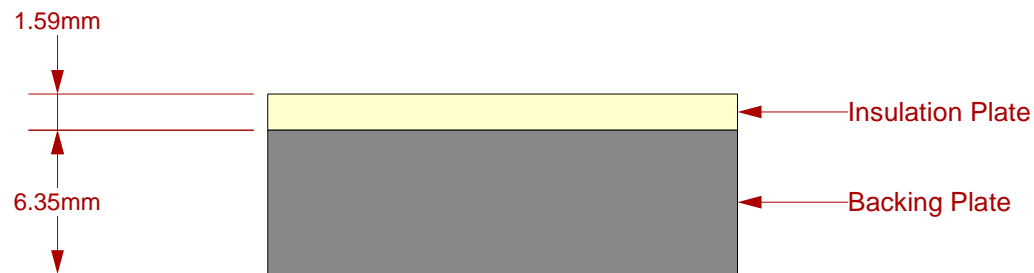
All dimensions are in mm unless stated otherwise

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	Drawing: M. Tully		Date: 4/2/2013	
	File: SBT-BGA-7006 Dwg		Modified:	


Top View



Side View



Description: Insulation Plate and Backing Plate

SBT-BGA-7006 Drawing		Status: Released	Scale: -	Rev: A
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	File: SBT-BGA-7006 Dwg		Modified:	

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)